Die Diesel Silloon Silloon 7440-21-3 0.80327 100 13.59 Wire Pure metal Aluminium (Al) 7429-90-5 0.0882 100.0 0.31800 Wire Pure metal Aluminium (Al) 7429-90-5 0.0882 100.0 6.48 Die Attach Lead alloy Tin (Sn) 7440-91-5 0.02867 2.0 6.79800 Die Attach Lead alloy Silver (Ag) 7440-91-5 0.02867 2.5 0.441 Lead alloy Silver (Ag) 7440-91-5 0.02867 2.5 0.441 Lead alloy Silver (Ag) 7440-91-6 0.02607 2.5 0.441 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Phosphorous (P) 7440-02-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Copper (U) 7440-02-0 0.01271 0.03 715828 Mound Polymer Epchlo	External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire Pure metal Aluminium (AI) 7429-90-5 0.0188 100.0 0.31809 Pure metal Aluminium (AI) 7429-90-5 0.38302 100.0 6.48 Burd Hatch Lead alloy Tin (Sn) 7440-31-5 0.02085 2.0 0.3528 Die Attach Lead alloy Silver (Ag) 7440-22-4 0.02607 2.5 0.441 Lead alloy Lead (Fa) T440-22-4 0.02607 2.5 0.441 Lead Frame Copper alloy Phosphorous (P) 7439-92-1 0.99574 95.5 16.8462 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Nickel (NI) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Copper alloy 7440-02-0 0.02171 0.03 0.717 Mould Copper alloy Polymer Subtotal 42.38018 0.0 715.8528 Polymer Pelpichioroby	Die		Silicon (Si)	7440-21-3	0.80327	100.0	13.59
Pure metal Aluminium (Al) 7429-90-5 0.38302 100.0 6.48				Subtotal	0.80327	100	13.59
Die Attach Lead alloy Tin (Sn) 7440-31-5 0.02085 2.0 0.3528 2.0 0.3528 2.0 0.3528 2.0 0.3528 2.0 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.441 2.0 0.02607 2.5 0.68462 2.0 0.02607 2.5 0.68462 2.0 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.5 0.02607 2.0	Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0188	100.0	0.31809
Die Attach Lead alloy Tin (Sn) 7440-31-5 0.02085 2.0 0.3528 2.0 0.3528 2.0 0.3528 2.0 0.441 2.0 2.5 0.441 2.0 2.5 0.441 2.0 2.5 0.441 2.0 2.0 2.5 0.441 2.0 2.0 2.5 2.0		Pure metal	Aluminium (Al)	7429-90-5	0.38302	100.0	6.48
Lead alloy Lead alloy Lead (Pb) 7440-22-4 0.02607 2.5 0.441				Subtotal	0.40182	200	6.79809
Lead alloy Lead (Pb) 7439-92-1 0.99574 95.5 16.8462 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151 Copper alloy Vickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151 Copper alloy Copper (Cu) 7439-89-6 0.04238 0.1 0.717 Mould Copper alloy Copper (Cu) 7440-50-8 42.31238 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.04394 3.8 34.58 Mould Compound Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Silica fused 60676-86-0 48.40917 90.0 819 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating<	Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02085	2.0	0.3528
Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01271 0.03 0.2151 Lead Frame Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04238 0.1 0.717 Mould Compound Copper alloy Copper (Cu) 7440-50-8 42.31238 99.84 715.8528 Mould Compound Polymer Phonol Formaldehyde resin (generic) 9003-35-4 2.04394 3.8 34.58 Polymer Pelpichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Sillica fused 60676-86-0 48.40917 90.0 819 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ethanol 64-17-5 0.10427 98.0 1.764 Coating Island 64-17-5 0.00213 2.0 0.036		Lead alloy	Silver (Ag)	7440-22-4	0.02607	2.5	0.441
Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01271 0.03 0.2151 Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04238 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 42.31238 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 8ubtotal 42.38018 100 717 Mould Compound Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Silica fused 60676-86-0 48.40917 90.0 819 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Filhanol 64-17-5 0.10427 98.0 1.764 Coating Filhanol 64-17-5 0.10427 98.0 1.764 Coating Filhanol 64-17-5 0.10427 9		Lead alloy	Lead (Pb)	7439-92-1	0.99574	95.5	16.8462
Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01271 0.03 0.2151				Subtotal	1.04266	100	17.64
Copper alloy Iron (Fe) 7439-89-6 0.04238 0.1 0.717	Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01271	0.03	0.2151
Copper alloy Copper (Cu) 7440-50-8 42.31238 99.84 715.8528 715.		Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01271	0.03	0.2151
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.04394 3.8 34.58 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Silica fused 60676-86-0 48.40917 90.0 819 Carbon Black Carbon black 1333-86-4 0.10758 0.2 1.82 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ithanol 64-17-5 0.10427 98.0 1.764 Coating Ithanol 64-17-5 0.00213 2.0 0.036 Subtotal 1.8 1.8 1.8 1.8 1.8		Copper alloy	Iron (Fe)	7439-89-6	0.04238	0.1	0.717
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.04394 3.8 34.58 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Silica fused 60676-86-0 48.40917 90.0 819 Carbon Black Carbon black 1333-86-4 0.10758 0.2 1.82 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Fiblanol 64-17-5 0.10427 98.0 1.764 Coating Fiblanol 919-30-2 0.00213 2.0 0.036 Fiblanol Subtotal 0.1064 100 1.8		Copper alloy	Copper (Cu)	7440-50-8	42.31238	99.84	715.8528
Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.04394 3.8 34.58 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.22728 6.0 54.6 Filler Silica fused 60676-86-0 48.40917 90.0 819 Carbon Black Carbon black 1333-86-4 0.10758 0.2 1.82 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ethanol 64-17-5 0.10427 98.0 1.764 Coating Ethanol 64-17-5 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8				Subtotal	42.38018	100	717
Filler Silica fused 60676-86-0 48.40917 90.0 819		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.04394	3.8	34.58
Carbon Black Carbon black 1333-86-4 0.10758 0.2 1.82 Subtotal 53.78797 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ethanol 64-17-5 0.10427 98.0 1.764 Subtotal 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8		Polymer		25928-94-3	3.22728	6.0	54.6
Subtotal 53.78797 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ethanol 64-17-5 0.10427 98.0 1.764 3-aminopropyltriethoxysilane 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8		Filler	Silica fused	60676-86-0	48.40917	90.0	819
Post-plating Pure metal Tin (Sn) 7440-31-5 1.47769 100.0 25 Coating Ethanol 64-17-5 0.10427 98.0 1.764 Subtotal 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8		Carbon Black	Carbon black	1333-86-4	0.10758	0.2	1.82
Coating Ethanol 64-17-5 0.10427 98.0 1.764 3-aminopropyltriethoxysilane 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8				Subtotal	53.78797	100	910
Coating Ethanol 64-17-5 0.10427 98.0 1.764 3-aminopropyltriethoxysilane 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8	Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.47769	100.0	25
3-aminopropyltriethoxysilane 919-30-2 0.00213 2.0 0.036 Subtotal 0.1064 100 1.8				Subtotal	1.47769	100	25
Subtotal 0.1064 100 1.8	Coating		Ethanol	64-17-5	0.10427	98.0	1.764
			3-aminopropyltriethoxysilane	919-30-2	0.00213	2.0	0.036
Total 99.99999 100 1691.82809				Subtotal	0.1064	100	1.8
				Total	99.99999	100	1691.82809

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